

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6024875

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YAOJIAN LIN	03/16/2015
WON KYOUNG CHOI	03/16/2015
KANG CHEN	03/16/2015
IVAN MICALLEF	07/03/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	STATS CHIPPAK PTE. LTD.
<b>Street Address:</b>	5 YISHUN STREET 23
<b>City:</b>	SINGAPORE
<b>State/Country:</b>	SINGAPORE
<b>Postal Code:</b>	768442
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16825567
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	480-499-9400
<b>Email:</b>	main@plgaz.com
<b>Correspondent Name:</b>	PATENT LAW GROUP: ATKINS AND ASSOCIATES
<b>Address Line 1:</b>	123 W. CHANDLER HEIGHTS ROAD, #12535
<b>Address Line 4:</b>	CHANDLER, ARIZONA 85248
<b>ATTORNEY DOCKET NUMBER:</b>	2515.0469 CON2
<b>NAME OF SUBMITTER:</b>	LISA ROSSETTI
<b>SIGNATURE:</b>	/Lisa Rossetti/
<b>DATE SIGNED:</b>	03/20/2020
<b>Total Attachments: 4</b>	
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source=16825567ASSIGNMENT#page2.tif	
source=16825567ASSIGNMENT#page3.tif	



ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING MICROELECTROMECHANICAL SYSTEMS (MEMS) PACKAGE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0469 and U.S. Provisional Application No. 61/952,620, filed March 13, 2014, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

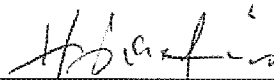
I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

16 March 2015

Date Signed



Signature for YAOJIAN LIN

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, WON KYOUNG CHOI of Singapore, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING MICROELECTROMECHANICAL SYSTEMS (MEMS) PACKAGE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0469 and U.S. Provisional Application No. 61/952,620, filed March 13, 2014, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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16 March 2015

Date Signed



Signature for WON KYOUNG CHOI

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KANG CHEN of Singapore, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING MICROELECTROMECHANICAL SYSTEMS (MEMS) PACKAGE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0469 and U.S. Provisional Application No. 61/952,620, filed March 13, 2014, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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16 March 2015  
\_\_\_\_\_  
Date Signed

  
\_\_\_\_\_  
Signature for KANG CHEN

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, IVAN MICALLEF of France, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING MICROELECTROMECHANICAL SYSTEMS (MEMS) PACKAGE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0469 and U.S. Provisional Application No. 61/952,620, filed March 13, 2014, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

30 JULY 2015  
Date Signed

  
Signature for IVAN MICALLEF